#### **ABSOLUTE MAXIMUM RATINGS**

IN12, IN34, FB1, FB2, EN1, EN2, EN3, EN4, OUT1,	Continuous Power Dissi
OUT2, REF to GND0.3V to +6.0V	16-Pin, 3mm x 3mm 7
OUT3,	(derate 20.8mW/°C a
OUT4 to GND0.3V to the lesser of $+$ 6V or (VIN34 $+$ 0.3V)	Operating Temperature
PGND1, PGND2 to GND0.3V to +0.3V	Junction Temperature
LX1, LX2 Current1.5A RMS	Storage Temperature Ra
LX1, LX2 to GND (Note 1)0.3V to (VIN12 + 0.3V)	Lead Temperature (solo

Continuous Power Dissipation ( $TA = +70^{\circ}C$ )	
16-Pin, 3mm x 3mm Thin QFN	
(derate 20.8mW/°C above +70°C)	1667mW
Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C

Note 1: LX\_ has internal clamp diodes to GND and IN12. Applications that forward bias these diodes should take care not to exceed the IC's package-dissipation limits.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

 $(V_{IN34} = V_{IN12} = 3.6V, T_A = -40$ °C to +85°C, unless otherwise noted. Typical values are at  $T_A = +25$ °C.) (Note 1)

PARAMETER	CONDITION	IS	MIN	TYP	MAX	UNITS
IN34 Supply Range	V <sub>IN12</sub> ≥ V <sub>IN34</sub>	V <sub>IN12</sub> ≥ V <sub>IN34</sub>				V
IN12 Supply Range	MAX8668, V <sub>IN12</sub> ≥ V <sub>IN34</sub>	MAX8668, V <sub>IN12</sub> ≥ V <sub>IN34</sub>			5.5	V
IN12 Suppy Range	MAX8667, V <sub>IN12</sub> ≥ V <sub>IN34</sub>		2.8		5.5	V
Shutdown Supply Current, I <sub>IN12</sub> + I <sub>IN34</sub>	V <sub>IN12</sub> = V <sub>IN34</sub> = 4.2V V <sub>EN</sub> _ = 0V	$T_A = +25^{\circ}C$ $T_A = +85^{\circ}C$		0.05	1	μA μA
No Load Supply Current, I <sub>IN12</sub> + I <sub>IN34</sub>	MAX8667ETEJS+, all regulators e	MAX8667ETEJS+, all regulators enabled				
UNDERVOLTAGE LOCKOUT			•			
IN12 UVLO	V <sub>IN12</sub> rising	V <sub>IN12</sub> rising				V
IINIZ UVLO	V <sub>IN12</sub> hysteresis	V <sub>IN12</sub> hysteresis				
IN34 UVLO	V <sub>IN34</sub> rising	1.5	1.6	1.7	V	
11134 0110	V <sub>IN34</sub> hysteresis			0.1		V
THERMAL SHUTDOWN						
Threshold	T <sub>A</sub> rising			+160		°C
Hysteresis				15		°C
REFERENCE						
Reference Bypass Output Voltage			0.591	0.600	0.609	V
REF Supply Rejection	$2.6V \le (V_{IN12} = V_{IN34}) \le 5.5V$			0.15		mV/V
LOGIC AND CONTROL INPUT	s		•			
EN_ Input Low Level	$1.7V \le V_{\text{IN}34} \le 5.5V$ $2.6V \le V_{\text{IN}12} \le 5.5V$				0.4	V
EN_ Input High Level	$1.7V \le V_{\text{IN}34} \le 5.5V$ $2.6V \le V_{\text{IN}12} \le 5.5V$					V
EN_ Input Leakage Current	V <sub>IN12</sub> = V <sub>IN34</sub> = 5.5V	-1	0.001	+1	μΑ	
STEP-DOWN CONVERTERS	- 1	T <sub>A</sub> = +85°C				1
Minimum Adjustable Output Voltage	MAX8668			0.6		V

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{IN34} = V_{IN12} = 3.6V, T_A = -40$ °C to +85°C, unless otherwise noted. Typical values are at  $T_A = +25$ °C.) (Note 1)

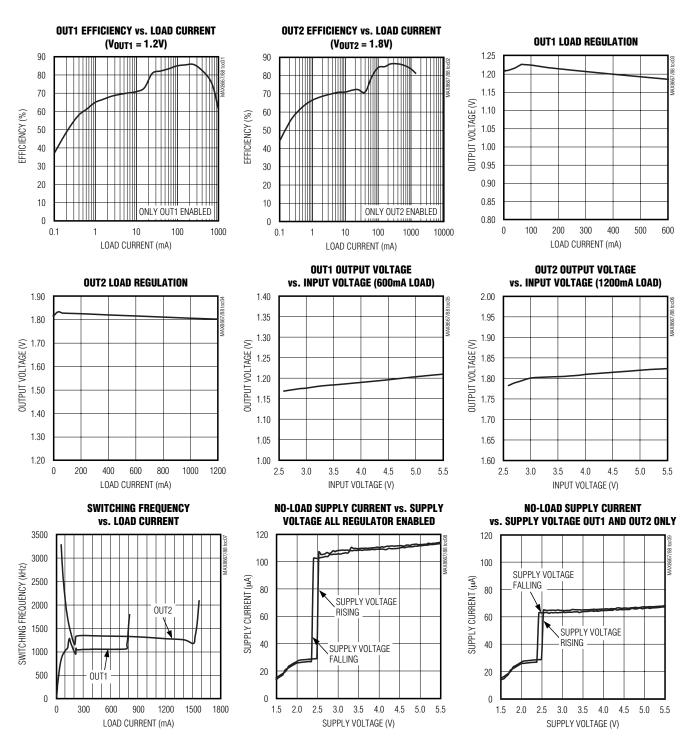
PARAMETER	CONDITION	MIN	TYP	MAX	UNITS		
Maximum Adjustable Output Voltage	MAX8668			3.3		V	
FB1, FB2 Regulation Voltage	MAX8668, no load,	$T_A = +25^{\circ}C$	0.588	0.600	0.612	V	
1 B1, 1 B2 Negalation Voltage	V <sub>FB</sub> _ falling	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	0.582	0.600	0.618	<b>V</b>	
OUT1, OUT2 Regulation Voltage	MAX8667ETEJS+, no load, VOUT_	$T_A = +25^{\circ}C$ $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	1.274	1.300	1.326	V	
COTT, COTZ riegulation voltage	falling	1.261	1.300	1.339	V		
FB1, FB2 Line Regulation	MAX8668, V <sub>IN12</sub> = 2.6V to 5.5V			0.01		%/V	
OUT1, OUT2 Line Regulation	MAX8667, V <sub>IN12</sub> = 2.8V to 5.5V			0.05		%/V	
FB1, FB2 Bias Current	MAX8668, shutdown mode			0.1		μΑ	
1 B1, 1 B2 Blas Current	MAX8668, $V_{FB1} = 0.5V$		0.01		μΑ		
OUT1 Current Limit	pMOSFET switch (I <sub>LIMP1</sub> )		700	900	1100	mA	
OOT I Current Elinit	nMOSFET rectifier (valley current)		500	750	1000	IIIA	
OUT2 Current Limit	pMOSFET switch (I <sub>LIMP2</sub> )		1333	1667	2000	m A	
OO12 Current Limit	nMOSFET rectifier (valley current)		1200	1500	1800	mA	
OUT1 On-Resistance	pMOSFET switch, I <sub>LX1</sub> = -400mA		0.3	0.6	0		
nMOSFET rectifier, I <sub>LX1</sub> = 400mA				0.3	0.6	Ω	
OLITA On Pagistanas	pMOSFET switch, I <sub>LX2</sub> = -400mA		0.12	0.27	0		
OUT2 On-Resistance	nMOSFET rectifier, I <sub>LX2</sub> = 400mA		0.12	0.27	Ω		
Rectifier-Off Current Threshold (I <sub>LXOFF</sub> )						mA	
	1.77	$T_A = +25^{\circ}C$	-1		+1		
LX Leakage Current	LX_ = 5.5V	T <sub>A</sub> = +85°C		0.1		μΑ	
Minimum On-Time				100		ns	
Minimum Off-Time				50		ns	
LDO REGULATORS							
Supply Current	Each LDO			20		μΑ	
Output Valtage Assurage	1mA load, T <sub>A</sub> = +25°C		-1.5		+1.5	%	
Output-Voltage Accuracy	1mA to 300mA load	-3.0		+3.0	70		
Line Regulation	V <sub>IN34</sub> = 3.6V to 5.5V, 1mA load			0.003		%/V	
Dropout Voltage	V <sub>IN34</sub> = 1.8V, 300mA load			130	250	mV	
Current Limit	Vout3, Vout4 90% of nominal value	re	375	420	465	mA	
Soft-Start Ramp Time	To 90% of final value			0.1		ms	
Output Noise	100Hz to 100kHz, 30mA load, Vol	$_{\rm JT3}$ and $V_{\rm OUT4} = 2.8V$		75		μV <sub>RMS</sub>	
Power-Supply Rejection Ratio	f < 1kHz, 30mA load		57		dB		
Shutdown Output Resistance			1		kΩ		
TIMING (See Figure 2)							
Dower On Time (town out)	OUT1, OUT2			25			
Power-On Time (tpwRON)	OUT3, OUT4		45			μs	
Enable Time (tax)	OUT1, OUT2			15		110	
Enable Time (t <sub>EN</sub> )	OUT3, OUT4			35		μs	
	•					•	

**Note 1:** All devices are 100% production tested at  $T_A = +25$ °C. Limits over the operating temperature range are guaranteed by design.

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### Typical Operating Characteristics

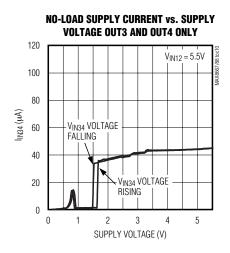
(V<sub>IN12</sub> = V<sub>IN34</sub> = 3.6V, circuit of Figure 4, V<sub>OUT1</sub> = 1.2V, V<sub>OUT2</sub> = 1.8V, V<sub>OUT3</sub> = 2.8V, V<sub>OUT4</sub> = 2.8V, T<sub>A</sub> = +25°C, unless otherwise noted.)

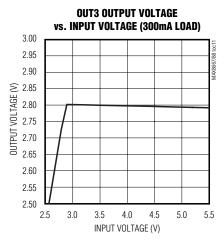


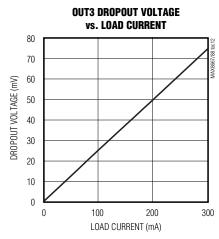
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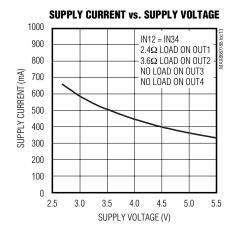
### Typical Operating Characteristics (continued)

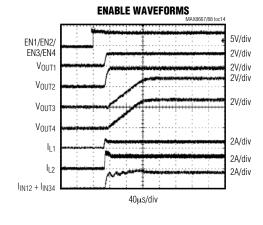
(V<sub>IN12</sub> = V<sub>IN34</sub> = 3.6V, circuit of Figure 4, V<sub>OUT1</sub> = 1.2V, V<sub>OUT2</sub> = 1.8V, V<sub>OUT3</sub> = 2.8V, V<sub>OUT4</sub> = 2.8V, T<sub>A</sub> = +25°C, unless otherwise noted.)

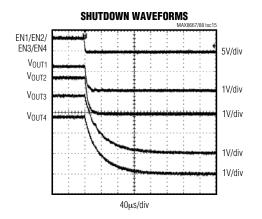


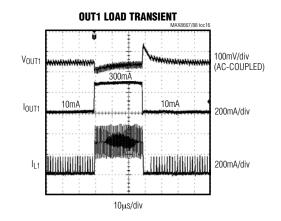






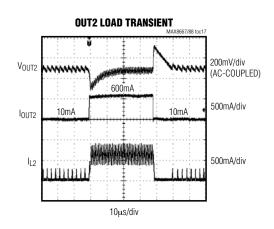


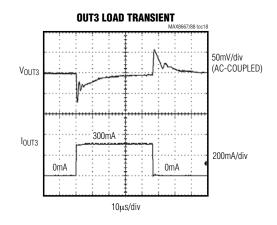


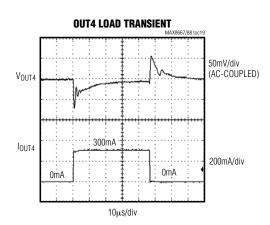


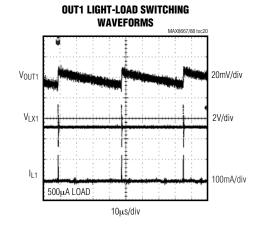
### Typical Operating Characteristics (continued)

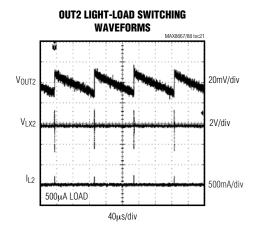
 $(V_{IN12} = V_{IN34} = 3.6V, \text{ circuit of Figure 4}, V_{OUT1} = 1.2V, V_{OUT2} = 1.8V, V_{OUT3} = 2.8V, V_{OUT4} = 2.8V, T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 

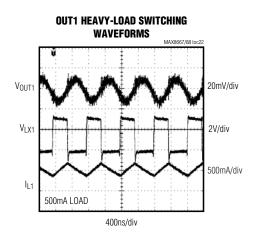






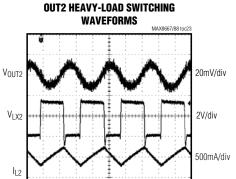


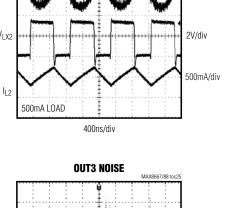


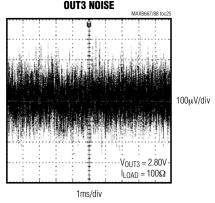


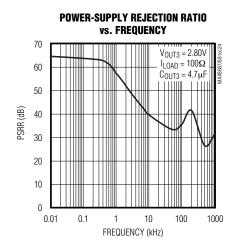
### Typical Operating Characteristics (continued)

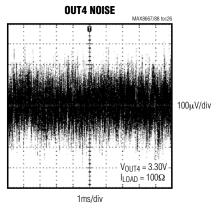
(V<sub>IN12</sub> = V<sub>IN34</sub> = 3.6V, circuit of Figure 4, V<sub>OUT1</sub> = 1.2V, V<sub>OUT2</sub> = 1.8V, V<sub>OUT3</sub> = 2.8V, V<sub>OUT4</sub> = 2.8V, T<sub>A</sub> = +25°C, unless otherwise noted.)











### **Pin Description**

	NA	ME	FUNCTION					
PIN	MAX8667	MAX8668						
1	EN3	EN3	Enable Input for Regulator 3. Drive EN3 high or connect to IN34 to turn on regulator 3. Drive low to turn off regulator 3 and reduce input quiescent current.					
2	OUT3	OUT3	Output of Regulator 3. Bypass OUT3 with a 4.7 $\mu$ F ceramic capacitor to GND. OUT3 is discharged to GND through an internal 1k $\Omega$ in shutdown.					
3	IN34	IN34	Input Voltage for LDO Regulators 3 and 4. Supply voltage range is from 1.7V to 5.5V. This supply voltage must not exceed V <sub>IN12</sub> . Connect a 4.7µF or larger ceramic capacitor from IN34 to ground.					
4	OUT4	OUT4	Output of Regulator 4. Bypass OUT4 with a 4.7 $\mu$ F ceramic capacitor to GND. OUT4 is discharged to GND through an internal 1k $\Omega$ in shutdown.					
5	EN4	EN4	Enable Input for Regulator 4. Drive EN4 high or connect to IN34 to turn on regulator 4. Drive low to turn off regulator 4 and reduce input quiescent current.					
6	GND	GND	Ground					
7	REF	REF	Reference Output. Bypass REF with a 0.01µF ceramic capacitor to GND.					
8	OUT2	_	Feedback Input for Regulator 2. Connect OUT2 directly to the output of step-down regulator 2.					
	_	FB2	Feedback Input for Regulator 2. Connect FB2 to the center of a resistor feedback divider between the output of regulator 2 and ground to set the output voltage. See the Setting the Output Voltages and Voltage Positioning					
9	PGND2	PGND2	Power Ground for Step-Down Regulator 2					
10	LX2	LX2	Inductor Connection for Regulator 2					
11	IN12	IN12	Input Voltage for Step-Down Regulators 1 and 2. Supply voltage range is from 2.6V to 5.5V. This supply voltage must not be less than $V_{IN34}$ . Connect a $10\mu F$ or larger ceramic capacitor from IN12 to ground.					
12	LX1	LX1	Inductor Connection for Regulator 1					
13	PGND1	PGND1	Power Ground for Step-Down Regulator 1					
14	OUT1	_	Feedback Input for Regulator 1. Connect OUT1 directly to the output of step-down regulator 1.					
	_	FB1	Feedback Input for Regulator 1. Connect FB1 to the center of a resistor feedback divider between the output of regulator 1 and ground to set the output voltage. See the Setting the Output Voltages and Voltage Positioning					
15	EN1	EN1	Enable Input for Regulator 1. Drive EN1 high or connect to IN12 to turn on step-down regulator 1. Drive low to turn off the regulator and reduce input quiescent current.					
16	EN2	EN2	Enable Input for Regulator 2. Drive EN2 high or connect to IN12 to turn on step-down regulator 2. Drive low to turn off the regulator and reduce input quiescent current.					
	EP	EP	Exposed Paddle. Connect to GND, PGND1, PGND2, and circuit ground.					

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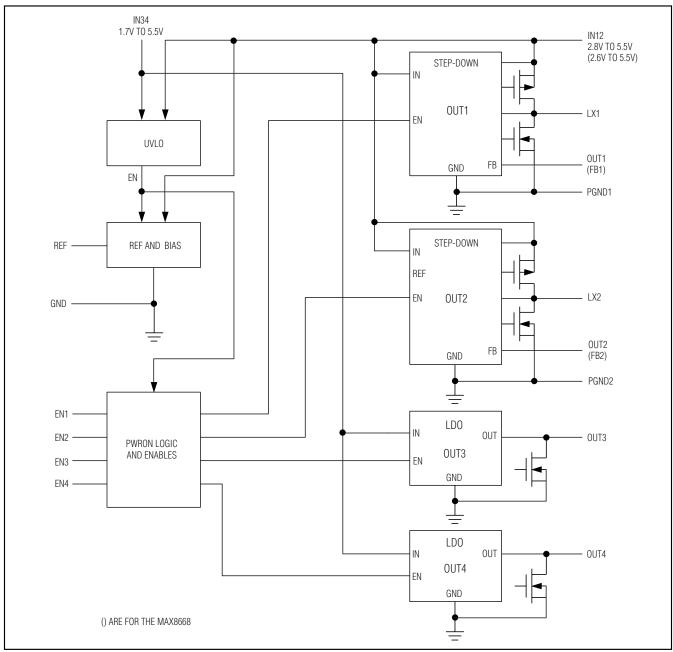


Figure 1. Functional Diagram

### **Detailed Description**

The MAX8667/MAX8668 dual step-down converters with dual low-dropout (LDO) linear regulators are intended to power low-voltage microprocessors or DSPs in portable devices. They feature high efficiency with small external component size. The step-down outputs are adjustable from 0.6V to 3.3V (MAX8668) or factory preset (MAX8667) with guaranteed output current of 600mA for OUT1 and 1200mA for OUT2. The 1.5MHz hysteretic-PWM control scheme allows for tiny external components and reduces no-load operating current to  $100\mu A$  (typ) with all regulators enabled. Dual, low-quiescent-current, low-noise LDOs operate down to 1.7V supply voltage. The MAX8667/MAX8668 have individual enable inputs for each output to facilitate any supply sequencing.

### Step-Down DC-DC Regulators (OUT1, OUT2)

#### Step-Down Regulator Architecture

The MAX8667/MAX8668 step-down regulators are optimized for high-efficiency voltage conversion over a wide load range, while maintaining excellent transient response, minimizing external component size, and minimizing output voltage ripple. The DC-DC converters (OUT1, OUT2) also feature an optimized on-resistance internal MOSFET switch and synchronous rectifier to maximize efficiency. The MAX8667/MAX8668 utilize a proprietary hysteretic-PWM control scheme that switches with nearly fixed frequency at up to 1.5MHz allowing for ultra-small external components. The step-down converter output current is guaranteed up to 600mA for OUT1 and 1200mA for OUT2.

When the step-down converter output voltage falls below the regulation threshold, the error comparator begins a switching cycle by turning the high-side p-channel MOSFET switch on. This switch remains on until the minimum on-time (ton) expires and the output voltage is in regulation or the current-limit threshold ( $I_{LIMP}$ ) is exceeded. Once off, the high-side switch remains off until the minimum off-time (toff) expires and the output voltage again falls below the regulation threshold. During this off period, the low-side synchronous rectifier turns on and remains on until either the high-side switch turns on or the inductor current reduces to the rectifier-off current threshold ( $I_{LXOFF} = 60$ mA typ). The internal synchronous rectifier eliminates the need for an external Schottky diode.

#### Input Supply and Undervoltage Lockout

The input voltage range of step-down regulators OUT1 and OUT2 is 2.6V to 5.5V. This supply voltage must be greater than or equal to the LDO supply voltage (V<sub>IN34</sub>).

A UVLO circuit prevents step-down regulators OUT1 and OUT2 from switching when the supply voltage is too low to guarantee proper operation. When  $V_{IN12}$  falls below 2.4V (typ), OUT1 and OUT2 are shut down. OUT1 and OUT2 turn on and begin soft-start when  $V_{IN12}$  rises above 2.5V (typ).

#### Soft-Start

When initially powered up, or enabled with EN\_, the step-down regulators soft-start by gradually ramping up the output voltage. This reduces inrush current during startup. See the startup waveforms in the *Typical Operating Characteristics* section.

#### **Current Limit**

The MAX8667/MAX8668 limit the peak inductor current of the p-channel MOSFET (I<sub>LIMP</sub>). A valley current limit is used to protect the step-down regulators during severe overload and output short-circuit conditions. When the peak current limit is reached, the internal p-channel MOSFET turns off and remains off until the output drops below regulation, the inductor current falls below the valley current-limit threshold, and the minimum off-time has expired.

#### Voltage Positioning

The OUT1 and OUT2 output voltages and voltage positioning of the MAX8668 are set by a resistor network connected to FB\_. With this configuration, a portion of the feedback signal is sensed on the switched side of the inductor, and the output voltage droops slightly as the load current is increased due to the DC resistance of the inductor. This output voltage droop is known as voltage positioning. Voltage positioning allows the load regulation to be set to match the voltage droop during a load transient, reducing the peak-to-peak output voltage deviation during a load transient, and reducing the output capacitance requirements.

#### Dropout

As the input voltage approaches the output voltage, the duty cycle of the p-channel MOSFET reaches 100%. In this state, the p-channel MOSFET is turned on constantly (not switching), and the dropout voltage is the voltage drop due to the output current across the onresistance of the internal p-channel MOSFET (RPCH) and the inductor's DC resistance ( $R_L$ ):

 $V_{DO} = I_{LOAD}(R_{PCH} + R_L)$ 

#### LDO Linear Regulators (OUT3, OUT4)

The MAX8667/MAX8668 contain two low-dropout linear regulators (LDOs), OUT3 and OUT4. The LDO output voltages are factory preset, and each LDO supplies

loads up to 300mA. The LDOs include an internal reference, error amplifier, p-channel pass transistor, and internal voltage-dividers. Each error amplifier compares the reference voltage to the output voltage (divided by the internal voltage-divider) and amplifies the difference. If the divided feedback voltage is lower than the reference voltage, the pass-transistor gate is pulled lower, allowing more current to pass to the outputs and increasing the output voltage. If the divided feedback voltage is too high, the pass-transistor gate is pulled up, allowing less current to pass to the output.

#### Input Supply and Undervoltage Lockout

The input voltage range of LDO regulators OUT3 and OUT4 is 1.7V to 5.5V. This supply voltage must be less than or equal to the voltage applied to IN12 ( $V_{IN34} \le V_{IN12}$ ).

An undervoltage lockout circuit turns off the LDO regulators when the input supply voltage is too low to guarantee proper operation. When V<sub>IN34</sub> falls below 1.5V (typ), OUT3 and OUT4 are shut down. OUT3 and OUT4 turn on and begin soft-start when V<sub>IN34</sub> rises above 1.6V (typ).

#### Soft-Start

When initially powered up, or enabled with EN\_, the LDOs soft-start by gradually ramping up the output voltage. This reduces inrush current during startup. The

soft-start ramp time is typically 100µs from the start of the soft-start ramp to the output reaching its nominal regulation voltage.

#### **Current Limit**

The OUT3 and OUT4 output current is limited to 375mA (min). If the output current exceeds the current limit, the corresponding LDO output voltage drops.

#### Dropout

The maximum dropout voltage for the linear regulators is 250mV at 300mA load. To avoid dropout, make sure the IN34 supply voltage is at least 250mV higher than the highest LDO output voltage.

#### **Thermal-Overload Protection**

Thermal-overload protection limits the total power dissipation in the MAX8667/MAX8668. Thermal-protection circuits monitor the die temperature. If the die temperature exceeds +160°C, the IC is shut down, allowing the IC to cool. Once the IC has cooled by 15°C, the IC is enabled again. This results in a pulsed output during continuous thermal-overload conditions. The thermal-overload protection protects the MAX8667/MAX8668 in the event of fault conditions. For continuous operation, do not exceed the absolute maximum junction temperature of +150°C. See the *Thermal Considerations* section for more information.

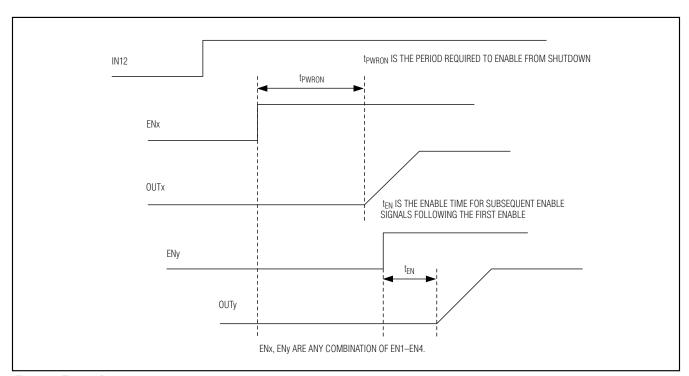


Figure 2. Timing Diagram

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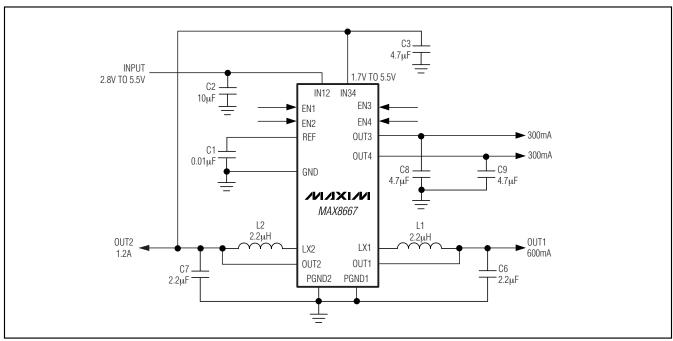


Figure 3. MAX8667 Typical Application Circuit

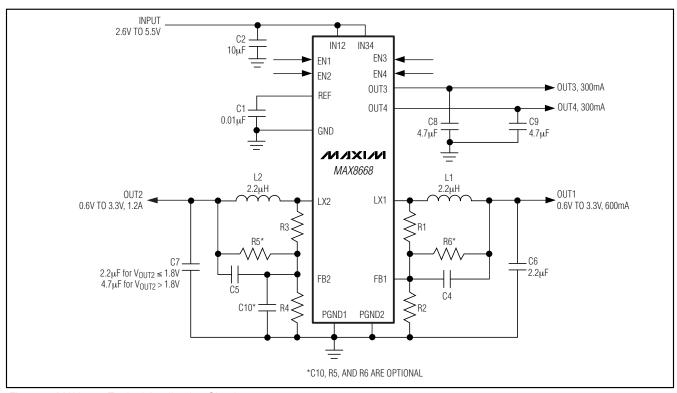


Figure 4. MAX8668 Typical Application Circuit

### **Applications Information**

### Setting the Output Voltages and Voltage Positioning

The LDO output voltages of the MAX8667/MAX8668, and the step-down outputs of the MAX8667 are factory preset. See the *Selector Guide* to find the part number corresponding to the desired output voltages.

The OUT1 and OUT2 output voltages of the MAX8668 are set by a resistor network connected to FB\_ as shown in Figure 5. With this configuration, a portion of the feedback signal is sensed on the switched side of the inductor (LX), and the output voltage droops slightly as the load current is increased due to the DC resistance of the inductor (DCR). This allows the load regulation to be set to match the voltage droop during a load transient (voltage positioning), reducing the peakto-peak output-voltage deviation during a load transient, and reducing the output capacitance requirements.

For the simplest method of setting the output voltage, R6 is not installed. Choose the value of R2 (a good starting value is  $100k\Omega$ ), and then calculate the value of R1 as follows:

$$R1 = R2 \times \left(\frac{V_{OUT}}{V_{FB}} - 1\right)$$

where VFB is the feedback regulation voltage (0.6V).

With the voltage set in this manner, the voltage positioning depends only on the DCR, and the maximum output voltage droop is:

$$\Delta V_{OUT(MAX)} = DCR \times I_{OUT(MAX)}$$

#### Setting the Output Voltages with Reduced Voltage Positioning

To obtain less voltage positioning than described in the previous section, use the following procedure for setting the output voltages. The OUT1 and OUT2 output voltages and voltage positioning of the MAX8668 are set by a resistor network connected to FB\_ as shown in Figure 5.

To set the output voltage ( $V_{OUT}$ ), first select a value for R2 (a good starting value is 100k $\Omega$ ). Then calculate the value of REQ (the equivalent parallel resistance of R1 and R6) as follows:

$$R_{EQ} = \left(\frac{V_{OUT}}{V_{EB}} - 1\right) \times R2$$

where V<sub>FB</sub> is the feedback-regulation voltage (0.6V).

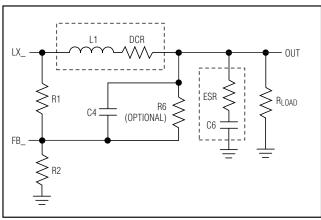


Figure 5. MAX8668 Feedback Network

Calculate the factor m based on the desired load-regulation improvement:

$$m = \frac{IOUT(MAX) \times DCR}{\Delta VOUT(DESIRED)}$$

where I<sub>OUT(MAX)</sub> is the maximum output current, DCR is the inductor series resistance, and  $\Delta$ V<sub>OUT(DESIRED)</sub> is the maximum allowable droop in the output voltage at full load. The calculated value for m must be between 1.1 and 2; m = 2 results in a 2x improvement in load regulation.

Now calculate the values of R1 and R6 as follows:

$$R1 = R_{EQ} \times m$$

$$R6 = R_{EQ} \times \frac{m}{m-1}$$

The value of R1 should always be lower than the value of R6.

#### **Power-Supply Sequencing**

The MAX8667/MAX8668 have individual enable inputs for each regulator to allow complete control over the power sequencing. When all EN\_ inputs are low, the IC is in low-power shutdown mode, reducing the supply current to less than 1µA. After one of the EN\_ inputs asserts high, the corresponding regulator begins soft-start after a delay of ten (see Figure 2). The first output enabled from shutdown mode or initially powering up the IC has a longer delay (tpwRON) as the IC exits the low-power shutdown mode.

#### **Inductor Selection**

The MAX8667/MAX8668 step-down converters operate with inductors between 2.2µH and 4.7µH. Low inductance values are physically smaller, but require faster switching, resulting in some efficiency loss. The inductor's DC current rating must be high enough to account

**Table 1. Recommended Inductors** 

MANUFACTURER	INDUCTOR	L (µH)	$R_L$ (m $\Omega$ )	CURRENT RATING (A)	L x W x H (mm)
FDK	MIPF2016		110	1.1	2.0 x 1.6 x 1.0
FDK	MIPF2520D	2.2	80	1.3	2.5 x 2.0 x 1.0
Murata	LQH32CN2R2M5	2.2	97	0.79	3.2 x 2.5 x 1.55
Murata	LQM31P	2.2	220	0.9	3.2 x 1.6 x 0.95
Sumida	CDRH2D09	2.2	120	0.44	3.2 x 3.2 x 1.0
TDK	GLF251812T	2.2	200	0.6	2.5 x 1.8 x 1.35
TOKO	D2812C	2.2	140	0.77	2.8 x 2.8 x 1.2
TOKO	MDT2520-CR	2.2	80	0.7	2.5 x 2.0 x 1.0
Wurth	TPC Series	2.2	55	1.8	4.0 x 4.0 x 1.1
vvurtn	TPC Series	4.7	124	1.35	4.0 x 4.0 x 1.1
Taiyo Yuden	CB2518T	2.2	90	0.51	2.5 x 1.8 x 2.0

for peak ripple current and load transients. The stepdown converter's unique architecture has minimal current overshoot during startup and load transients and in most cases, an inductor capable of 1.3x the maximum load current is acceptable.

For output voltages above 2V, when light-load efficiency is important, the minimum recommended inductor is 2.2µH. For optimum voltage-positioning load transients, choose an inductor with DC series resistance in the  $50m\Omega$  to  $150m\Omega$  range. For higher efficiency at heavy loads (above 200mA) and minimal load regulation, keep the inductor resistance as small as possible. For light-load applications (up to 200mA), higher resistance is acceptable with very little impact on performance.

#### **Capacitor Selection**

#### Input Capacitors

The input capacitor for the step-down converters (C2 in Figures 3 and 4) reduces the current peaks drawn from the battery or input power source and reduces switching noise in the IC. The impedance of C2 at the switching frequency should be very low. Surface-mount ceramic capacitors are a good choice due to their small size and low ESR. Make sure the capacitor maintains its capacitance over temperature and DC bias. Ceramic capacitors with X5R or X7R temperature characteristics generally perform well. A  $10\mu F$  ceramic capacitor is recommended.

A  $4.7\mu F$  ceramic capacitor is recommended for the LDO input capacitor (C3 in Figure 3).

#### Step-Down Output Capacitors

The step-down output capacitors (C6 and C7 in Figures 3 and 4) are required to keep the output-voltage ripple

small and to ensure regulation loop stability. These capacitors must have low impedance at the switching frequency. Surface-mount ceramic capacitors are a good choice due to their small size and low ESR. Make sure the capacitor maintains its capacitance over temperature and DC bias. Ceramic capacitors with X5R or X7R temperature characteristics generally perform well. The output capacitance can be very low. For most applications, a 2.2 $\mu$ F ceramic capacitor is sufficient. For C7 of the MAX8668, a 2.2 $\mu$ F (VOUT2  $\leq$  1.8V) or a 4.7 $\mu$ F (VOUT2 > 1.8V) ceramic capacitor is recommended. For optimum load-transient performance and very low output ripple, the output capacitor value in  $\mu$ F should be equal to or greater than the inductor value in  $\mu$ H.

#### Feed-Forward Capacitor

The feed-forward capacitors on the MAX8668 (C4 and C5 in Figure 4) set the feedback loop response, control the switching frequency, and are critical in obtaining the best efficiency possible. Small X7R and C0G ceramic capacitors are recommended.

For OUT1, calculate the value of C4 as follows:

$$C4 = 1.2 \times 10^{-5} (s/V) \times (VOUT / R1)$$

For OUT2, calculate the value of C5 and C10 as follows:

 $C_{ff} = 1.2 \times 10^{-5} (s/V) \times (V_{OUT} / R3)$ 

 $C_{ff} = C_5 + (C_{10} / 2)$ 

 $(C10 / C5) + 1 = (V_{OUT} / V_{FB})$ , where V<sub>FB</sub> is 0.6V.

Rearranging the formulas:

 $C10 = 2 \times C_{ff} \times (V_{OUT} - V_{FB})/(V_{OUT} + V_{FB})$ 

 $C5 = C_{ff} - (C10 / 2)$ 

14 \_\_\_\_\_\_/W|

C10 is needed if  $V_{OUT} > 1.5V$  or  $V_{IN12}$  can be less than  $V_{OUT} / 0.65$ .

#### LDO Output Capacitor and Stability

Connect a 4.7µF ceramic capacitor between OUT3 and GND, and a second 4.7µF ceramic capacitor from OUT4 to GND. For a constant loading above 10mA, the output capacitors can be reduced to 2.2µF. The equivalent series resistance (ESR) of the LDO output capacitors affects stability and output noise. Use output capacitors with an ESR of 0.1 $\Omega$  or less to ensure stable operation and optimum transient response. Surfacemount ceramic capacitors have very low ESR and are commonly available. Connect these capacitors as close as possible to the IC's pins to minimize PCB trace inductance.

#### **Thermal Considerations**

The maximum package power dissipation of the MAX8667/MAX8668 is 1667mW. Make sure the power dissipated by the MAX8667/MAX8668 does not exceed this rating. The total IC power dissipation is the sum of the power dissipation of the four regulators:

$$P_{D} = P_{D1} + P_{D2} + P_{D3} + P_{D4}$$

Estimate the OUT1 and OUT2 power dissipations as follows:

$$P_{D1} = I_{OUT1} \times V_{OUT1} \times \frac{1 - \eta}{\eta}$$

$$P_{D2} = I_{OUT2} \times V_{OUT2} \times \frac{1 - \eta}{\eta}$$

where  $R_L$  is the inductor's DC resistance, and  $\eta$  is the efficiency (see the *Typical Operating Characteristics* section).

Calculate the OUT3 and OUT4 power dissipations as follows:

$$P_{D4} = I_{OUT4} \times (V_{IN34} - V_{OUT4})$$

The maximum junction temperature of the MAX8667/MAX8668 is +150°C. The junction-to-case thermal resistance ( $\theta_{JC}$ ) of the MAX8667/MAX8668 is 6.9°C/W. When mounted on a single-layer PCB, the junction to ambient thermal resistance ( $\theta_{JA}$ ) is about 64°C/W. Mounted on a multilayer PCB,  $\theta_{JA}$  is about 48°C/W. Calculate the junction temperature of the MAX8667/MAX8668 as follows:

$$T_J = T_A + P_D \times \theta_{JA}$$

where  $T_A$  is the maximum ambient temperature. Make sure the calculated value of  $T_J$  does not exceed the  $+150^{\circ}C$  maximum.

#### **PCB Layout**

High switching frequencies and relatively large peak currents make PCB layout a very important aspect of design. Good design minimizes excessive EMI on the feedback paths and voltage gradients in the ground plane, both of which can result in instability or regulation errors. Connect the input capacitors as close as possible to the IN\_ and PGND\_ pins. Connect the inductor and output capacitors as close as possible to the IC and keep the traces short, direct, and wide.

The feedback network traces are sensitive to inductor magnetic field interference. Route these traces away from the inductors and noisy traces such as LX. Keep the feedback components close to the FB\_ pin.

Connect GND and PGND\_ to the ground plane. Connect the exposed paddle to the ground plane with one or more vias to help conduct heat away from the IC

Refer to the MAX8668 evaluation kit for a PCB layout example.

### Ordering Information (continued)

PART	PKG CODE	TOP MARK
MAX8667ETEHR+	T1633-4	AFJ
MAX8667ETEJS+	T1633-4	AFQ
MAX8668ETEA+	T1633-4	AER
MAX8668ETEP+	T1633-4	AFK
MAX8668ETEQ+	T1633-4	AFR
MAX8668ETET+	T1633-4	AFS
MAX8668ETEU+	T1633-4	AFL
MAX8668ETEV+	T1633-4	AFT
MAX8668ETEW+	T1633-4	AFU
MAX8668ETEX+	T1633-4	AFV

All MAX8667/MAX8668 parts are in a 16-pin, thin QFN, 3mm x 3mm package and operate in the -40°C to = +85°C extended temperature range.

#### **Selector Guide**

PART	OUT1 (V)	OUT2 (V)	OUT3 (V)	OUT4 (V)
MAX8667ETEAA+	1.20	1.80	2.80	2.80
MAX8667ETEAB+	1.20	1.80	2.85	2.85
MAX8667ETEAC+	1.20	1.80	1.20	1.20
MAX8667ETECQ+	1.60	1.80	2.80	1.20
MAX8667ETEHR+	1.80	1.20	2.60	2.80
MAX8667ETEJS+	1.30	1.30	3.30	2.70
MAX8668ETEA+	ADJ	ADJ	2.80	2.80
MAX8668ETEP+	ADJ	ADJ	3.30	1.80
MAX8668ETEQ+	ADJ	ADJ	2.80	1.20
MAX8668ETET+	ADJ	ADJ	3.30	3.30
MAX8668ETEU+	ADJ	ADJ	3.30	2.80
MAX8668ETEV+	ADJ	ADJ	3.30	2.50
MAX8668ETEW+	ADJ	ADJ	3.30	3.00
MAX8668ETEX+	ADJ	ADJ	2.80	1.80

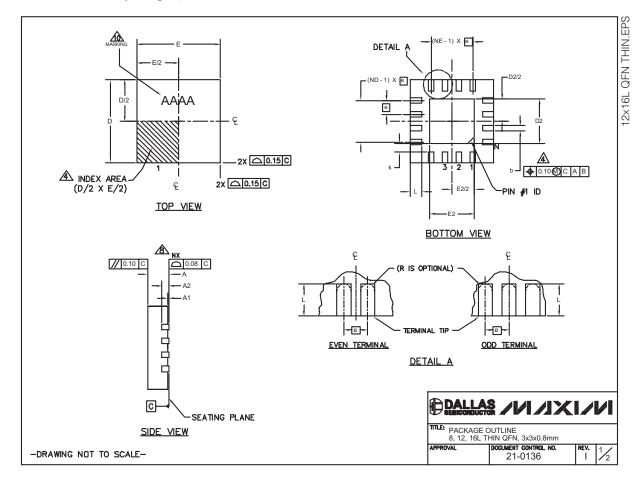
**Chip Information** 

PROCESS: BiCMOS

<sup>+</sup>Denotes a lead-free package.

### **Package Information**

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



### **Package Information (continued)**

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to www.maxim-ic.com/packages.)

PKG	8L 3x3			1	12L 3x3			16L 3x3			
REF.	MIN. NOM. MAX.		MIN.	NOM.	MAX.	MIN.	NOM.	MAX.			
Α	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80		
b	0.25	0.30	0.35	0.20	0.25	0.30	0.20	0.25	0.30		
D	2.90	3.00	3.10	2.90	3.00	3.10	2.90	3.00	3.10		
Е	2.90	3.00	3.10	2.90	3.00	3.10	2.90	3.00	3.10		
е	0.65 BSC.			0.50 BSC.			0.50 BSC.				
L	0.35	0.55	0.75	0.45	0.55	0.65	0.30	0.40	0.50		
N		8			12 3			16			
ND		2						4			
NE	2		2 3				4				
A1	0	0.02	0.05	0	0.02	0.05	0	0.02	0.05		
A2	0.20 REF			0	.20 RE	F	0	.20 RE	F		
k	0.25	-	-	0.25	-	-	0.25	-	-		

EXPOSED PAD VARIATIONS										
PKG.		D2			E2		PIN ID	JEDEC		
CODES	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	PINID	JEDEC		
TQ833-1	0.25	0.70	1.25	0.25	0.70	1.25	0.35 x 45°	WEEC		
T1233-1	0.95	1.10	1.25	0.95	1.10	1.25	0.35 x 45°	WEED-1		
T1233-3	0.95	1.10	1.25	0.95	1.10	1.25	0.35 x 45°	WEED-1		
T1233-4	0.95	1.10	1.25	0.95	1.10	1.25	0.35 x 45°	WEED-1		
T1633-2	0.95	1.10	1.25	0.95	1.10	1.25	0.35 x 45°	WEED-2		
T1633F-3	0.65	0.80	0.95	0.65	0.80	0.95	0.225 x 45°	WEED-2		
T1633FH-3	0.65	0.80	0.95	0.65	0.80	0.95	0.225 x 45°	WEED-2		
T1633-4	0.95	1.10	1.25	0.95	1.10	1.25	0.35 x 45°	WEED-2		
T1633-5	0.95	1.10	1.25	0.95	1.10	1.25	0.35 x 45°	WEED-2		

#### NOTES:

- 1. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
- N IS THE TOTAL NUMBER OF TERMINALS.
- JESD 95-1 SPP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.
- ⚠ DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.20 mm AND 0.25 mm
- 6 ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.
- DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
- COPLANARITY APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- DRAWING CONFORMS TO JEDEC MO220 REVISION C. MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
- 11. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY. 12. WARPAGE NOT TO EXCEED 0.10mm
- -DRAWING NOT TO SCALE-

DALLAS /VI/JXI/VI PACKAGE OUTLINE

8, 12, 16L THIN QFN, 3x3x0.8mm

DOCUMENT CONTROL NO.

21-0136

**Revision History** 

Pages changed at Rev 1: 1, 12, 14, 18

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